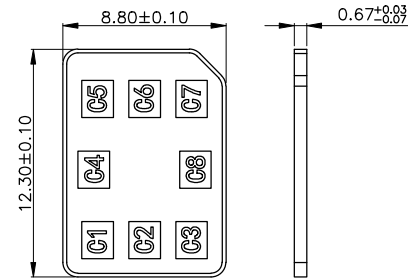
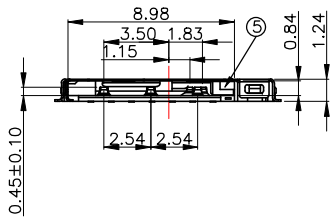
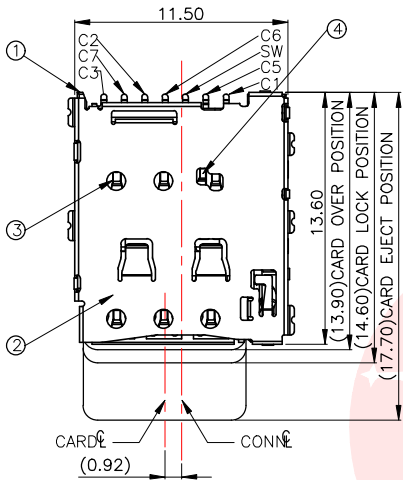
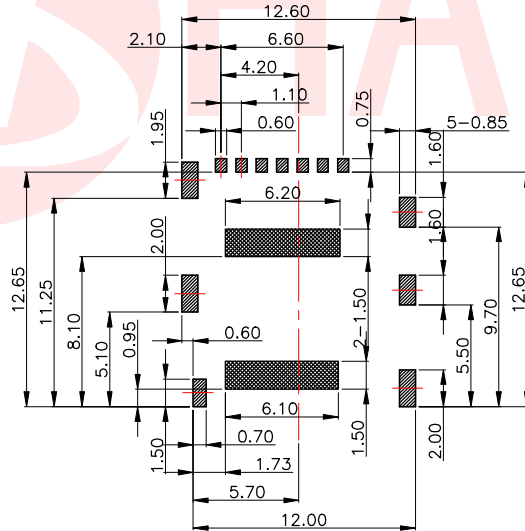
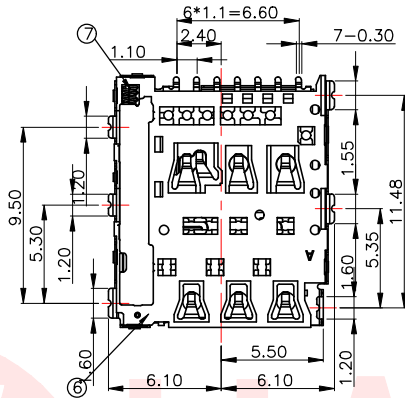




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



NANO-SIM CARD

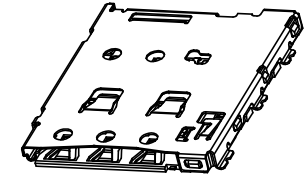
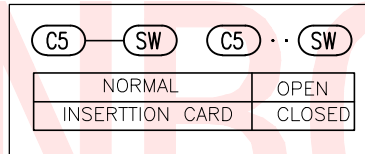


SMT SOLDER AREA.  
 NO PATTERN AREA

RECOMMENDED PCB LAYOUT  
 ALL TOLERANCE ±0.05MM

Nano SIM Circuit Description:

PIN No.	FUNCTION
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



NOTES:

- FINISH:
  - CONTACT: 50u"MIN NICKEL UNDER PLATED, 1u"MIN GOLD PLATING ON CONTACT AREA, GOLD FLASH PLATING ON SOLDERING AREA
  - SHELL: 30u"MIN NICKEL UNDER PLATED; 1u"MIN GOLD PLATING ON SOLDERING AREA.
- ELECTRICAL REQUIREMENTS:
  - RATED CURRENT: 0.5A
  - CONTACT RESISTANCE: 50mΩ MAX
  - INSULATION RESISTANCE: 1000MΩ MIN 200V DC FOR 1 MINUTE
  - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTE.
- MECHANICAL REQUIREMENTS:
  - DURABILITY: 3000 CYCLES MIN.
- ENVIRONMENTAL REQUIREMENTS:
  - OPERATING TEMP: -30°C~+85°C
  - STORAGE TEMP: -40°C~+85°C
- RECOMMENDED PROCESS CONDITION: IR-REFLOW, PEAK TEMPERATURE AND TIME: 250°C, 5-10S
- METALMASK THICKNESS 0.10MM MIN

NO.	DESCRIPTION	Q'TY	Material
7	SPRING	1	THERMOPLASTIC RATING UL94V-0
6	LINK	1	STAINLESS STEEL
5	SLIDE	1	STAINLESS STEEL
4	DETECT PIN	1	COPPER ALLOY
3	CONTACT	1	COPPER ALLOY
2	SHELL	1	STAINLESS STEEL
1	HOUSING	1	LCP UL94V-0

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X :±0.30 X.X :±0.20 X.XX :±0.10  
 ANGLES: X :±2° X.X :±1°



东莞市汉博电子科技有限公司  
 DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	1.24 NANO SIM PUSH CONN CUSTOMER			
DWN	xiong	PART NO. SNO-1420		
CHKD	lee	SCALE: 1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET: 10F 1	REV: A4

CUSTOMER COPY